



IEEE Council on Electronic Design Automation

ASP-DAC 2023 Tutorials: Call for Proposals

The [ASP-DAC 2023](#) Organizing Committee invites Tutorial proposals to be held during the 28th Asia and South Pacific Design Automation Conference (ASP-DAC 2023) from 16-19 January 2023. ASP-DAC is the annual international conference on VLSI design automation in Asia and South Pacific region, one of the most active regions of design and fabrication of silicon chips in the world.

ASP-DAC 2023 tutorials offer participants from different technical backgrounds the chance to explore innovative trends and learn new techniques from experts in the field. All tutorials will be 3 hours (or 1.5 hours) of intense introductions to specific topics and presented during the tutorial time slots. Suitable tutorial topics range from emerging research areas to established techniques of practical and industrial relevance.

The suggested topics include (but are not limited to) design, methodology, design automation fundamentals, system architectures, edge computing, automotive electronics, hardware, and embedded system security, machine learning, and the Internet of Things.

Important Dates

Tutorial Proposal Submission Deadline: 31 August 2022

Notification of Acceptance: 30 September 2022

Final Version Deadline: 9 January 2023

For more information, please visit the ASP-DAC [web-site](#).

Call for Papers: IEEE Journal on Exploratory Solid-State Computational Devices and Circuits special topic on "Spintronic Devices for Energy Efficient Computing"

This special topic of the [IEEE Journal on Exploratory Solid-State Computational Devices and Circuits](#) (JxCDC) will publish original recent research centered

around spintronic logic and memory devices for energy efficient computing, covering the research topics from new spintronic physics, new spintronic materials, to novel spintronic devices, to spintronic circuits and spintronic computing systems.

Important Dates

Submission Deadline: 5 September 2022

First Notification: 19 September 2022

Revision Submission: 17 October 2022

Final Decision: 14 November 2022

Publication Online: 1 December 2022

View the call for papers [here](#).

Call for Papers: IEEE Design&Test special issue on "Silicon Lifecycle Management (SLM)"

This special issue is dedicated to various aspect of Silicon Lifecycle Management. It aims to cover diverse aspects of this topic from design, EDA, on-chip infrastructure for test, debug, reliability, and security as well as data analytics.

Important Dates

Open For Submissions: 1 August 2022

Submission Deadline: 15 November 2022

Notification First Round: 31 January 2023

Revision Submission: 31 March 2023

Final Decision: 15 May 2023

Tentative Publication: Fall 2023

View the call for papers [here](#).

Register for ICCAD 2022

[ICCAD](#) is the premier forum to explore the new challenges, present leading-edge innovative solutions, and identify emerging technologies in the electronic design automation research areas. The

41st edition of the conference to be held in San Diego, California, USA from 30 October - 3 November 2022!

Authors are expected to present on-site at ICCAD 2022 unless there are travel challenges from their home country.

Take advantage of reduced, early registration rates by **15 September!**

Register [here](#).

CAD for Assurance Webinar 12 August

The [CAD for Assurance](#) webinar series is an educational initiative that provides CEDA members with access to relevant CAD tools to use. This includes information on major CAD tools the research community has developed over the past decade, including open-source license-free or ready-for-licensing tools, associated metrics, relevant publications, and video-demos.

The series will continue on 12 August 2022 with a panel presentation "Hardware Assurance vs. AI: Friend or Foe?" by Mike Borza (Synopsys), Brian Night (Microsoft), Pompei Len Orlando (Air Force Research Lab), Antonio de la Serna (Siemens), Peilin Song (IBM), and Samuel M Weber (Office of Naval Research)

Registration is free for the webinars, however is required in order to attend. Additional information can be found on the CEDA CAD for Assurance [website](#).

Register for FDL 2022

The [2022 Forum on Specification & Design Languages](#) (FDL) is a well-established international forum to exchange experiences and promote new trends in the application of languages, their associated design methods, and tools for the design of electronic systems. FDL stimulates scientific and controversial discussions within and in-between scientific topics as described below.

Register [here](#).

IEEE Autonomous UAV Competition

The next IEEE autonomous UAV competition will be held in August - November. This is a two-stage challenge. The first stage is online only by a simulator and will start on 10 August 2022. Finalists will be

selected to enter the second stage. The final competition will be held on November 1. The teams will be invited to visit the [Purdue UAS Research and Test Facility](#) and launch physical UAVs.

Travel grants will be available, up to \$2,000 USD per team (including international teams). If you are interested in participating, or you know anyone that may be interested, please join the slack channel for updates. Click [here](#) to join.

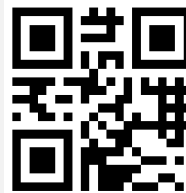
Click [here](#) for the rules.

A similar competition was held on April 9 2022. This video summarizes the competition: <https://youtu.be/uISFK83FSmQ>.

This November challenge will be more difficult than the one held in April. The ground rover will move faster and there will be more tunnels.

The competition is supported by the [National Science Foundation](#) and the [IEEE Computer Society](#).

Click [here](#) to visit the competition website.



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Please send contributions to Agnieszka Dubaj

 [Contributions Form](#)

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IEEE Embedded Systems Letters is open for submissions

Visit bit.ly/ESLsubmissions

IEEE Design & Test is open for submissions

Visit bit.ly/DTsubmissions